

## Final Product/Process Change Notification

Document #: FPCN20386XB Issue Date: 15 February 2016

Title of Change:	Qualification of ON Semiconductor Vietnam (OSV) for the Assembly and Test of the listed SCR products in DPAK package.		
Proposed first ship date:	22 May 2016		
Contact information:	Contact your local ON Semiconductor Sales Office or <gk.sua@onsemi.com></gk.sua@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office or <dong.ta@onsemi.com></dong.ta@onsemi.com>		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <cheanching.sim@onsemi.com></cheanching.sim@onsemi.com>		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change or earlier upon customer approval.  ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>		
Change Part Identification:	Products from ON Semiconductor Vietnam (OSV) will be marked with site code "VN" prior to date code.		
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other		
Change Sub-Category(s):  Manufacturing Site Change/ Manufacturing Process Char	Shipping/ Fackaging/ Ivial king		
Sites Affected:  All site(s)  not ap	plicable ON Semiconductor site(s):  ON Dong Nai Province, Vietnam ON Seremban, Malaysia		

### **Description and Purpose:**

This is an updated notification of FPCN 20386 issued on 20<sup>th</sup> Feb, 2014 to include additional SCR devices. This FPCN announces the planned capacity expansion of ON Semiconductor's assembly and test operations of DPAK discrete packaged products, currently built at ON Semiconductor Seremban, Malaysia facility to ON Semiconductor Vietnam (OSV).

Upon the expiration of this FPCN, SCR devices may be processed at either location. These products have been qualified to commodity/commercial requirements. These products will continue being Pb-free, Halide free and RoHS compliant.

### **Reliability Data Summary:**

#### **QV DEVICE NAME: MCR12DSNT4G**

PACKAGE: DPAK

FACKAGE. DEAK						
Test	Specification	Condition	Interval	Results		
HTRB	JESD22-A108	Ta= 90°C, 80% max rated V	1008 hrs	0/84		
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/84		
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta= +25°C, delta Tj= 100°C On/off = 2min	15000 cyc	0/84		
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/84		
H3TRB	JESD22-A101	85°C, 85% RH, 18.8psig, bias	1008 hrs	0/84		
AC	JESD22-A102	121°C, 100% RH, 15psig, unbiased	96 hrs	0/84		
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C		0/336		
RSH	JESD22- B106	Ta= 265°C, 10 sec		0/30		
SD JSTD002		Ta= 245°C, 10 sec		0/15		

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Electrical Characteristic Summary: Electrical characteristics are not impacted.				
List of Affected Standard Parts:				
Part Number	Qualification Vehicle			
MCR12DCMT4G	MCR12DSNT4G			
MCR8DCNT4G	MCR12DSNT4G			
MCR8DSNT4G	MCR12DSNT4G			

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